



AF/2800

Attorney Docket SEL 173

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of

Ohtani et al.

Serial No.: 09/535,836

Filed: March 28, 2000

For: Semiconductor Device Having  
Multi-layer Wiring

Art Unit: 2811

Examiner: H. Vu

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first  
class mail in an envelope addressed to:

Commissioner for Patents  
Washington, D.C. 20231

on March 7, 2002

Rachelle Hammerquist

Rachelle Hammerquist 3702  
Signature Date

RECEIVED  
APR - 1 2002  
TECHNOLOGY CENTER 2800  
4/2/02  
6/1/02

Commissioner for Patents  
Washington, D.C. 20231

AMENDMENT C (AFTER FINAL)

Sir:

In response to the Final Rejection dated January 7, 2002, please enter the following  
amendment in the above-identified application.

IN THE CLAIMS:

Please amend the claims as follows:

41. (Amended) The semiconductor device according to claim 40, wherein said first wiring is  
selected from the group consisting of aluminum and a material predominantly composed of aluminum.

21

42. (Amended) The semiconductor device according to claim 40, wherein said second wiring  
is selected from the group consisting of titanium and a material predominantly composed of titanium.